



PRODUCT IDENTIFICATION

JRPI	1265	P	-	100	M
Type	Size	Material		Inductance	Tol.

FEATURES

1. Shielded construction.
2. Capable of corresponding high frequency
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.
7. Operating temperature -40~+125°C
(Including self - temperature rise)

Marking and Date code:

Marking ex: 10 (μH) → 100

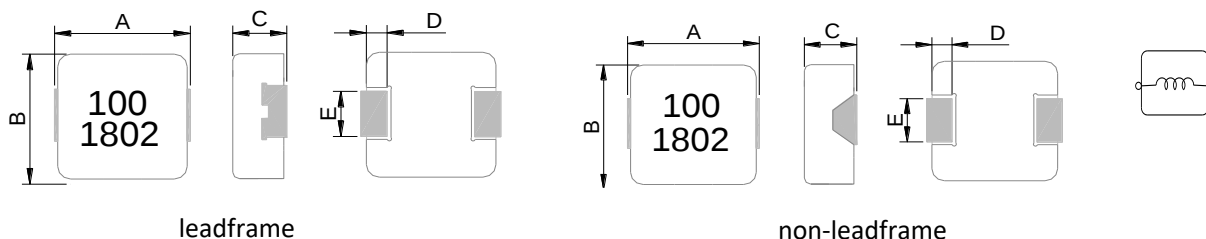
Date code

18 02 → year and weekly

APPLICATIONS

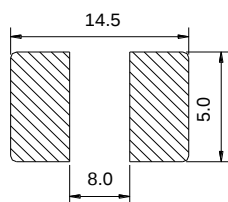
1. DC/DC converters in distributed power systems.
2. DC/DC converter for Field Programmable Gate Array(FPGA).
3. Battery powered devices.
4. Thin type on-board power supply module for exchanger.
5. VRM for server.
6. High current, low profile POL converters.
7. PDA/notebook/desktop/server and battery powered devices.

DIMENSIONS (mm)



印字:黑色100及D/C 1802 (18年,02週期)(依實際生產日期而定)

Recommend PC Board Pattern



Note:

1. PCB layout is referred to standard IPC-7351B
2. The above PCB layout reference only.
3. Recommend solder paste thickness at 0.15mm and above.

Part No.	Size (mm)				
	A	B	C	D	E
JRPI 1265P	13.5 ± 0.5	12.6 ± 0.2	6.2 ± 0.3	2.3 ± 0.3	See spec table

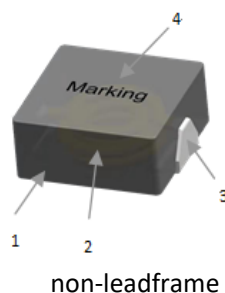
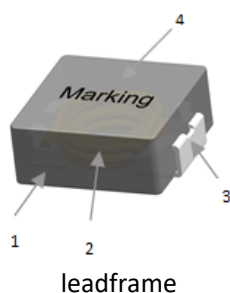
SERIES LIST

No.	Part No.	L	RDC		Isat		Irms		E	Type
		(μ H)	Typ.	Max.	Typ	Max	Typ	Max	(mm) ± 0.3	
1	JRPI 1265P-R10N	0.10 $\pm$ 30%	0.2	0.25	120.0	115.0	65.0	60.0	4.7	non-leadframe
2	JRPI 1265P-R22M	0.22 $\pm$ 20%	0.4	0.46	112.0	105.0	53.0	42.0	4.7	non-leadframe
3	JRPI 1265P-R33M	0.33 $\pm$ 20%	0.6	0.70	75.0	65.0	46.0	36.0	4.7	non-leadframe
4	JRPI 1265P-R68M	0.68 $\pm$ 20%	1.25	1.50	55.0	46.0	36.5	33.0	4.0	non-leadframe
5	JRPI 1265P-1R0M	1.0 $\pm$ 20%	1.5	1.80	45.0	36.0	33.0	29.0	4.0	non-leadframe
6	JRPI 1265P-1R5M	1.5 $\pm$ 20%	2.2	2.53	35.0	30.0	29.0	25.0	4.0	non-leadframe
7	JRPI 1265P-1R8M	1.8 $\pm$ 20%	3.2	3.6	31.0	27.0	27.0	23.0	4.7	leadframe
8	JRPI 1265P-2R2M	2.2 $\pm$ 20%	3.7	4.2	28.5	24.0	25.0	21.0	4.7	leadframe
9	JRPI 1265P-3R3M	3.3 $\pm$ 20%	5.3	6.2	27.0	22.5	22.0	19.0	4.7	leadframe
10	JRPI 1265P-4R7M	4.7 $\pm$ 20%	6.8	8.0	25.0	21.0	20.0	17.0	4.7	leadframe
11	JRPI 1265P-5R6M	5.6 $\pm$ 20%	8.3	9.8	23.0	19.5	18.0	15.0	4.7	leadframe
12	JRPI 1265P-6R8M	6.8 $\pm$ 20%	9.8	11.3	21.0	18.0	16.5	14.0	4.7	leadframe
13	JRPI 1265P-8R2M	8.2 $\pm$ 20%	12.0	13.8	19.0	17.0	15.0	12.5	4.7	leadframe
14	JRPI 1265P-100M	10 $\pm$ 20%	13.0	15.8	17.0	15.0	13.0	11.0	4.7	leadframe
15	JRPI 1265P-150M	15 $\pm$ 20%	22	26	13.5	12.0	11.0	9.5	4.7	leadframe
16	JRPI 1265P-220M	22 $\pm$ 20%	31	35	10.0	9.0	10.0	8.0	4.7	leadframe
17	JRPI 1265P-330M	33 $\pm$ 20%	46	55	9.0	8.0	9.0	6.5	4.7	leadframe
18	JRPI 1265P-470M	47 $\pm$ 20%	58	67	7.6	6.8	8.0	5.7	4.7	leadframe
19	JRPI 1265P-680M	68 $\pm$ 20%	82	100	6.0	5.0	5.8	4.8	4.7	leadframe
20	JRPI 1265P-820M	82 $\pm$ 20%	110	132	5.0	4.2	5.0	4.0	4.7	leadframe
21	JRPI 1265P-101M	100 $\pm$ 20%	140	161	5.0	4.0	5.0	3.8	4.7	leadframe

Note:

1. Test Frequency: 100KHz /1V
2. All test data referenced to 25°C ambient
3. Saturation Current (Isat) will cause L0 to drop approximately 30%.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.
Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. Irms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.
7. Rated DC Current : The less value which is Irms or Isat.

Materials

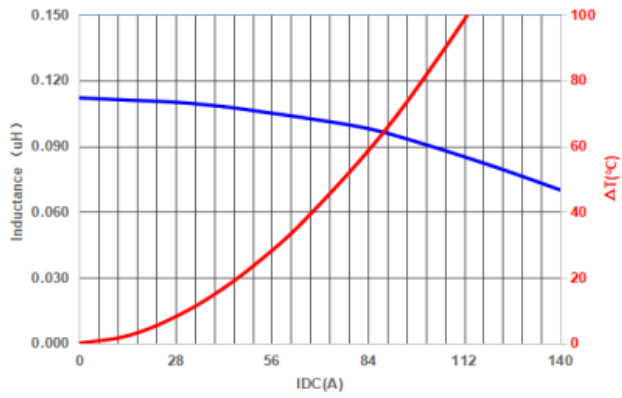


NO	Items	Materials
1	Core	Alloy Powder
2	Wire	Polyester Wire or equivalent
3	Clip	100% Pb free solder(Ni+Sn---Plating)

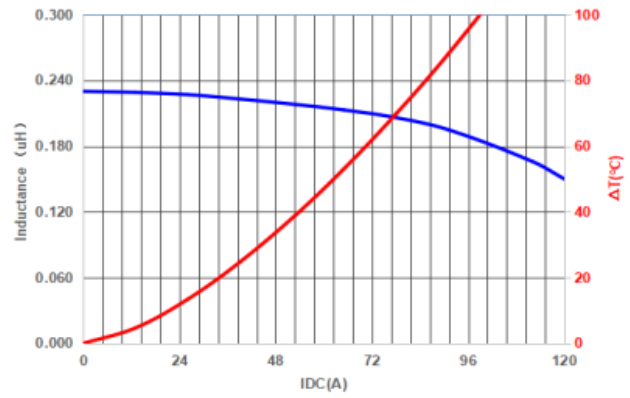
NO	Items	Materials
1	Core	Alloy Powder
2	Wire	Polyester Wire or equivalent
3	Solder	100% Pb free solder

TYPICAL PERFORMANCE CURVES

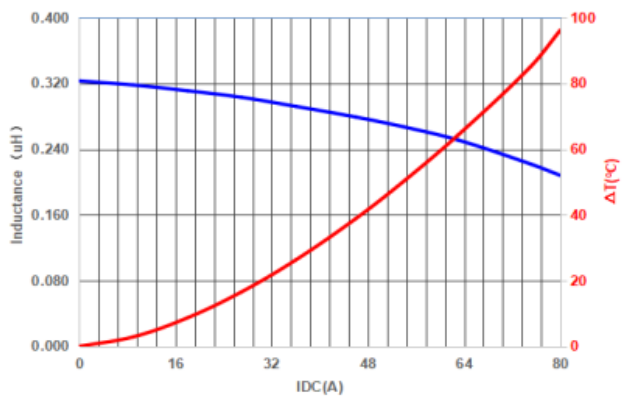
JRPI 1265P-R10



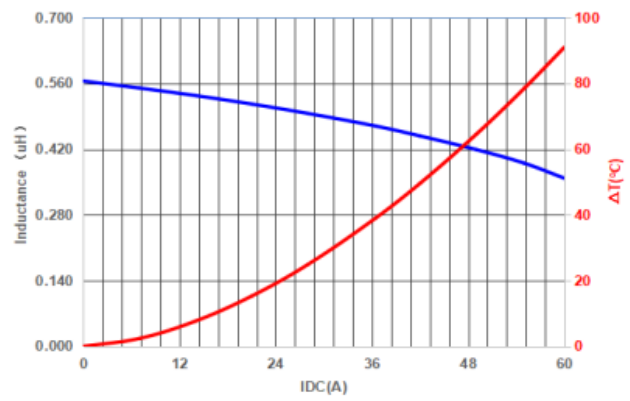
JRPI 1265P-R22



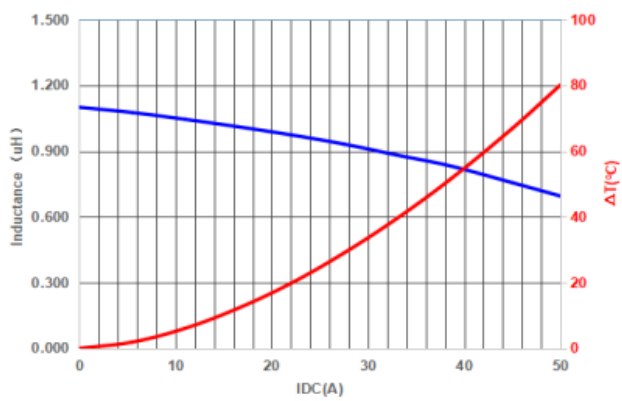
JRPI 1265P-R33



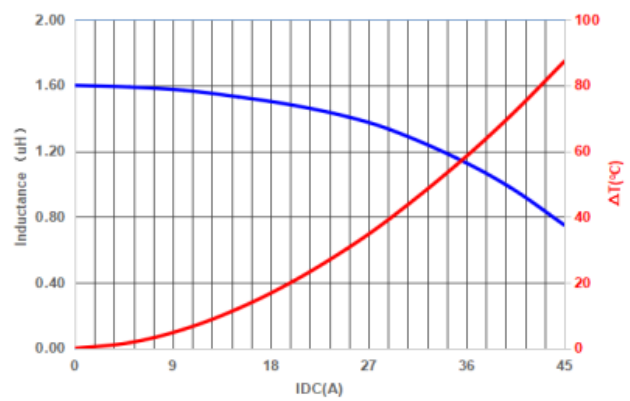
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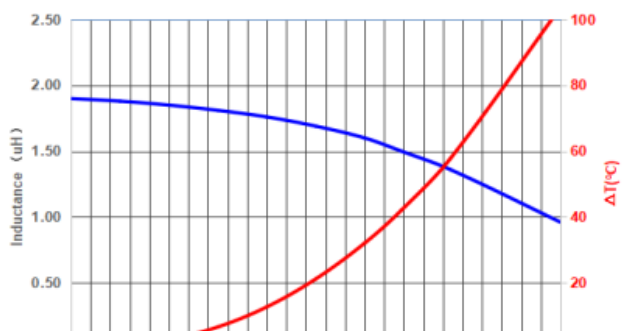
JRPI 1265P-1R0



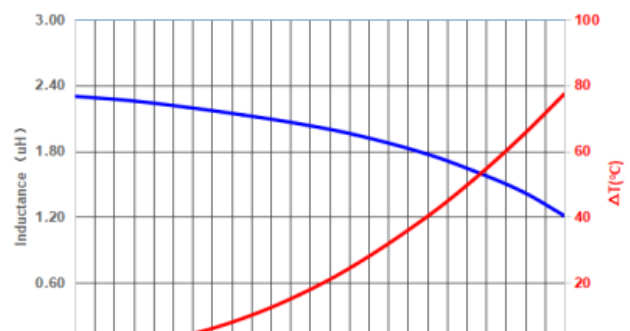
JRPI 1265P-1R5

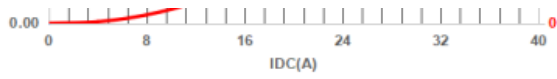


JRPI 1265P-1R8



JRPI 1265P-2R2

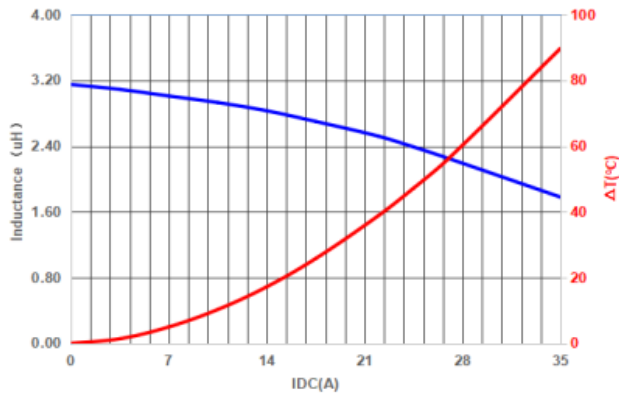




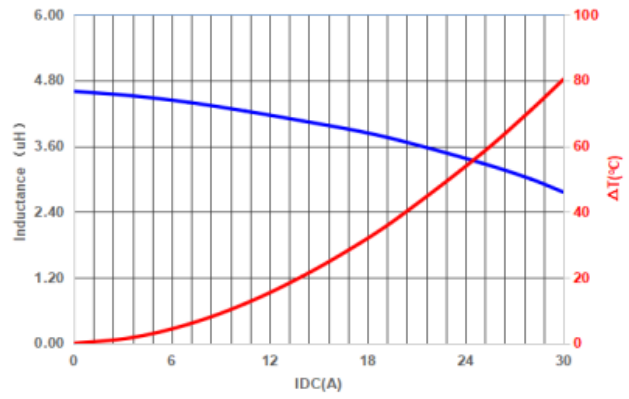
JRPI 1265P-3R3



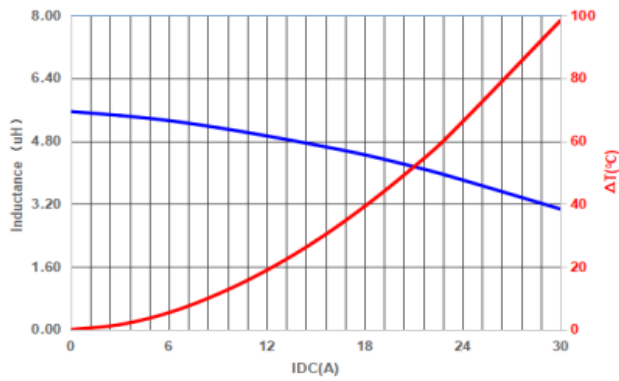
JRPI 1265P-4R7



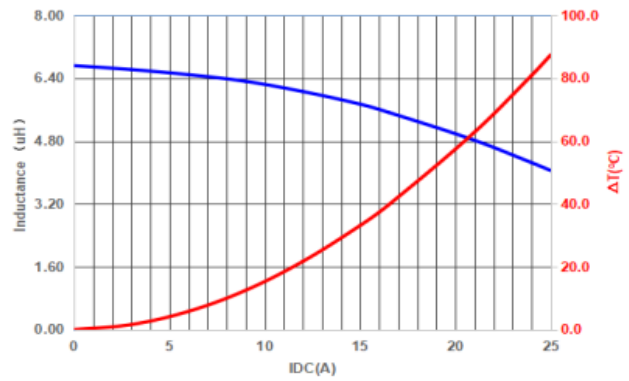
JRPI 1265P-5R6



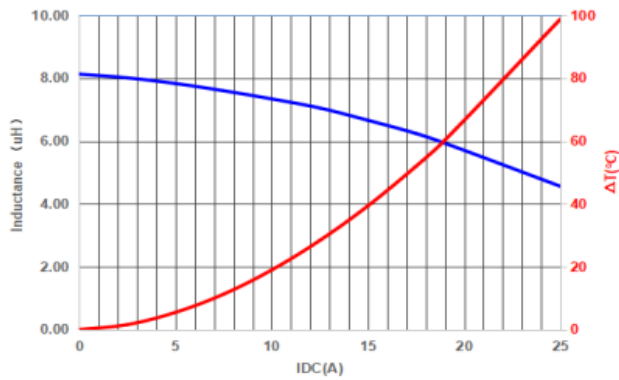
JRPI 1265P-6R8



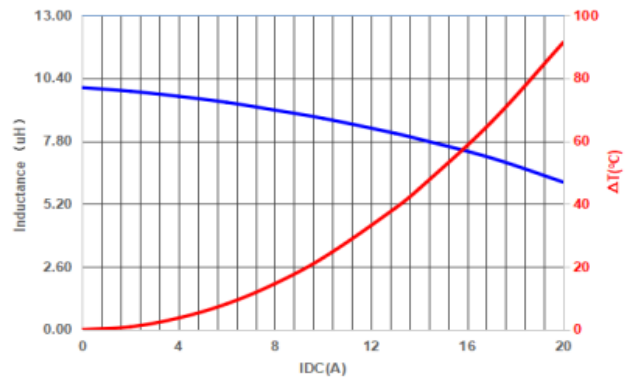
JRPI 1265P-8R2



JRPI 1265P-100

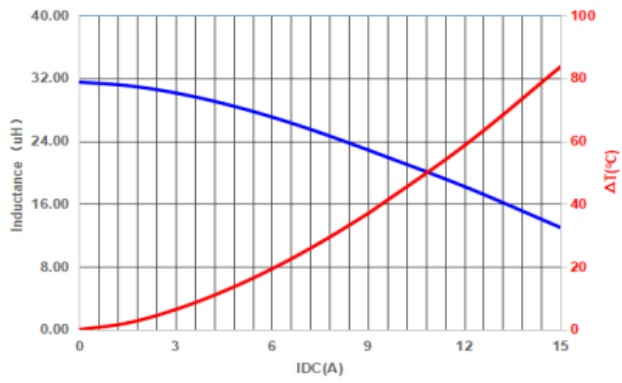


JRPI 1265P-150

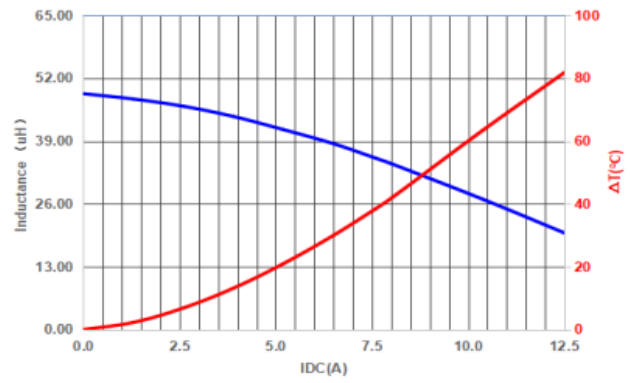


JRPI 1265P-220

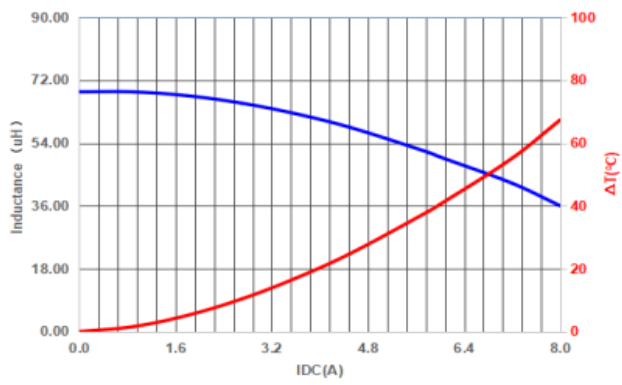
JRPI 1265P-330



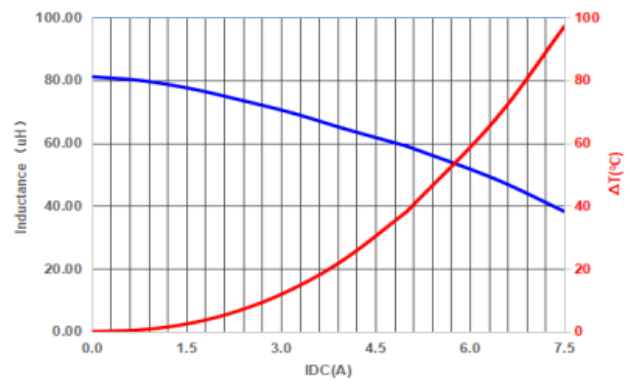
JRPI 1265P-470



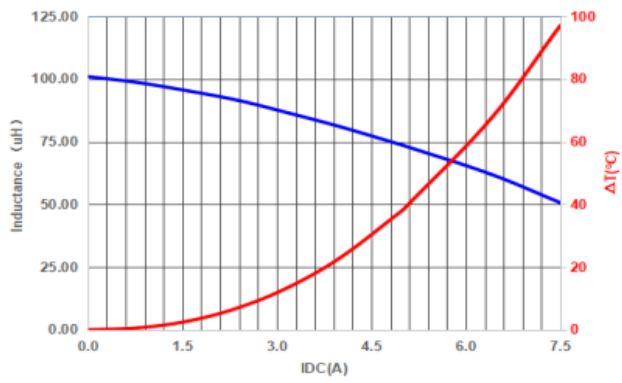
JRPI 1265P-680



JRPI 1265P-820

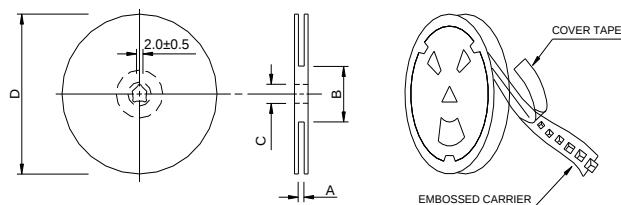


JRPI 1265P-101



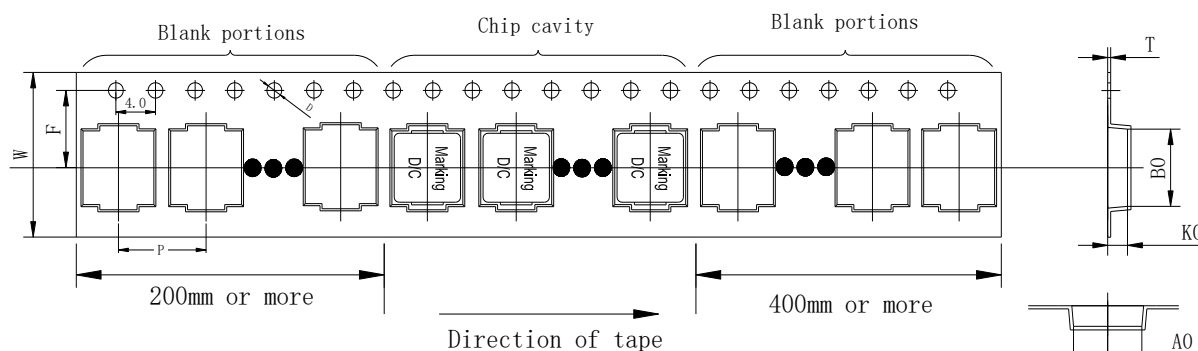
Packaging Information

• Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	$24.4 \pm 2/-0$	100 ± 2	$13 \pm 0.5/-0.2$	330

• Tape Dimension



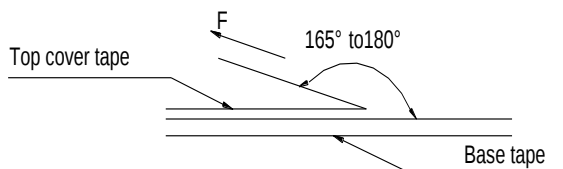
Ao(mm)	Bo(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)	D(mm)
12.9 ± 0.1	14.1 ± 0.1	7.0 ± 0.1	16.0 ± 0.1	24 ± 0.3	11.5 ± 0.1	0.35 ± 0.1	1.5 ± 0.1

• Packaging Quantity

Size	Reel
JRPI 1265P	500

• Tearing Off Force

The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions (referenced ANSI/EIA-481-D-2008 of 4.11 standard)



Tearing Speed mm	Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)
$300 \pm 10\%$	5~35	45~85	860~1060

■ Application Notice

- Storage Conditions(component level)

To maintain the solderability of terminal electrodes:

1. Products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40°C and 60% RH.
3. Recommended products should be used within 12 months form the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.